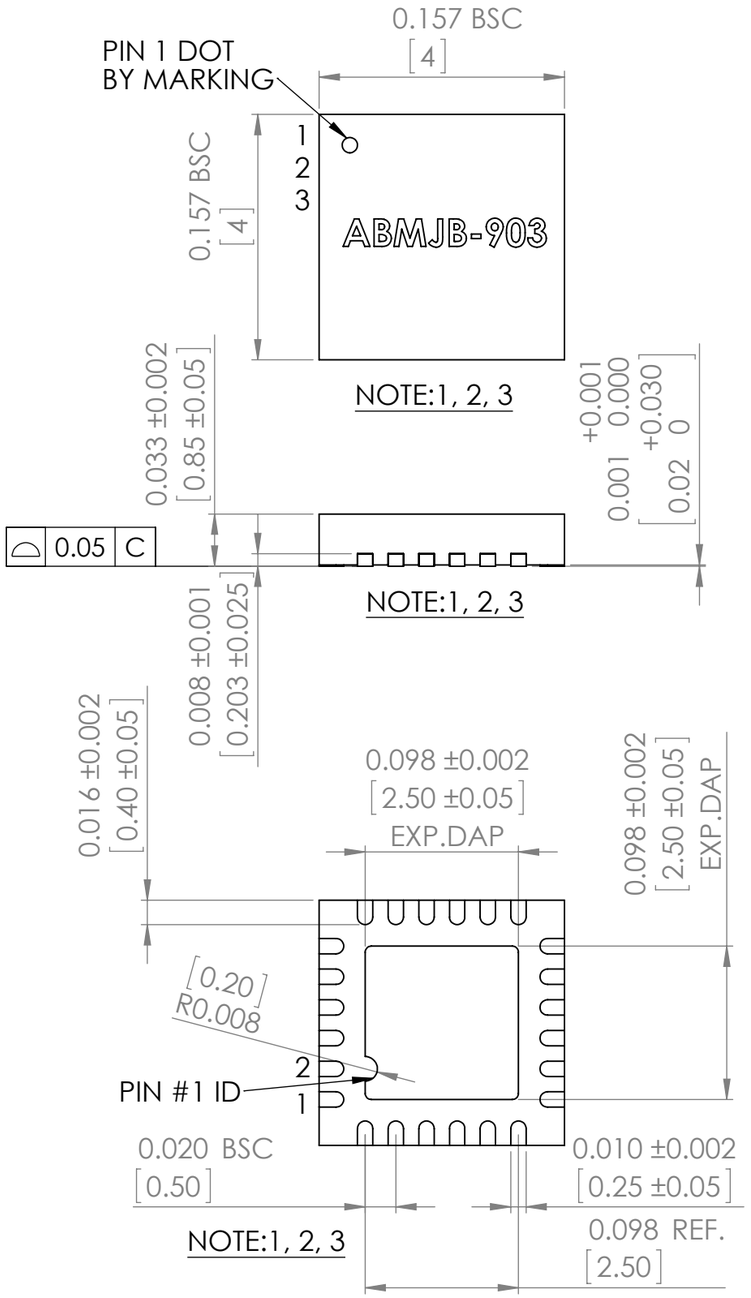
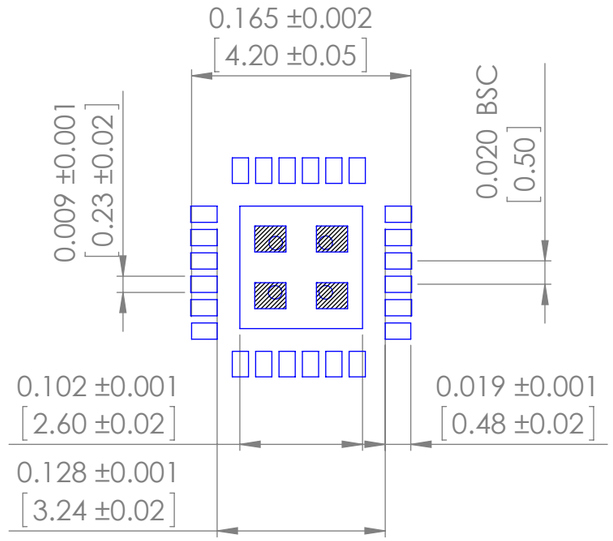
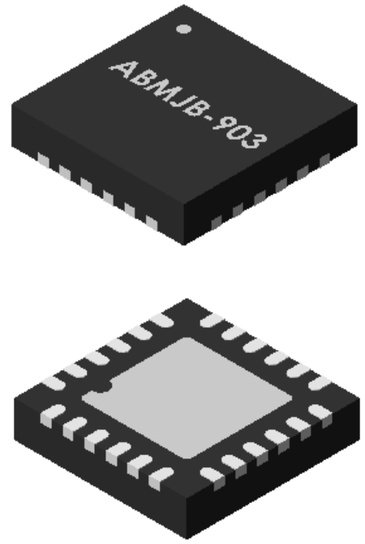


Recommended Land Pattern



Pin No.	Configuration.
22	Q
23	/Q
3	REFIN
12	OE
1,20	VDD
17,24	VDDO
2,8,13,14 15,21	VSS
4,5,7,9 11,16,18	DNC
6,10,19	DNC
ePad	Exposed Pad



Notes:
1. Max Package warpage is 0.05mm.
2. Max allowable burr is 0.076mm in all directions.
3. Pin 1 is on top and will be laser marked.
4. Red circles in land pattern indicate thermal vias. Size should be 0.30-0.35M in diameter and should be connected to GND for max thermal performance.
5. Green rectangles (shaded area) indicate solder stencil opening on exposed pad area.Size should be 1.00 x 1.00 mm in size, 1.20mm pitch.

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN INCH(MM)
SURFACE FINISH:
TOLERANCES:
LINEAR:
ANGULAR:

FINISH:

DEBUR AND BREAK SHARP EDGES

DO NOT SCALE DRAWING

REVISION -

	NAME	SIGNATURE	DATE
DRAWN	-		
CHK'D	XXXXXX		
APPV'D			
MFG			
Q.A			

MATERIAL:

WEIGHT:

ABRACON CORPORATION
30332 Esperanza, Rancho Santa margarita, California 92688

TITLE:

DWG NO. ABMJB-903

A3

SCALE:10:1

SHEET 1 OF 1